

Attorney Docket No.: 29273/516

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor

:

Shigeo MORIYAMA, et al.

Serial No.

09/462,912

Filed

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For

October 28, 1998

POLISHING APPARATUS AND METHOD FOR PRODUCING

SEMICONDUCTORS USING THE APPARATUS

Group Art Unit

3723

Assistant Commissioner for Patents Washington D.C. 20231

## **RESPONSE TO OFFICE ACTION**

SIR:

In response to the Office Action dated March 13, 2001, the due date being extended by the attached Petition for Extension of Time, please amend the application as follows:

## IN THE CLAIMS:

Please amend claims 1, 5, 10 and 11 as follows:

amend claims 1, 3, 10 and 11 as follows.

1. (Amended) A polishing apparatus which imparts relative motion between a layer with a concave portion and a convex portion on a semiconductor wafer and a polishing tool to polish the surface of said workpiece by a polishing surface of said polishing tool, comprising:

a dressing tool for forming a surface roughness on the polishing surface of said polishing tool;

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